



1714 ~~4~~

PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

October 10, 2003

Applicants : Tetsuo NISHIKAWA et al
Title : THERMOPLASTIC RESIN COMPOSITION
Serial No. : 09/973 646 Group: 1714
Confirmation No.: 6210
Filed : October 9, 2001 Examiner: Shosho
Atty. Docket No.: Nanjo Case 1
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RECEIVED
OCT 22 2003
TC 1700

Sir:

Herewith is an amendment in the above-identified application.

[] Applicant claims small entity status. See 37 CFR 1.27.

[] The additional filing fee has been calculated as shown below:

For	No. Filed	No. Extra	(X) LG Entity	RATE	() SM Entity	Fee
Basic Fee				\$770.00	\$385.00	\$
Total Claims	(11 - 20 = 0)		x \$	18.00	x \$	9.00
Indep. Claims	(2 - 3 = 0)		x \$	86.00	x \$	43.00
[] Multiple Dep. Claim			+	\$290.00	+	\$145.00
* * * TOTAL FILING FEE * * *						\$ 0.00

[X] Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by one month. The extension fee is: \$110.00.

[X] A Check for \$110.00 is enclosed to cover fees.

[X] Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

IN DUPLICATE

TFC/smd


Terryence F. Chapman Reg. No. 32 549

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on October 10, 2003.

130.10/03


Terryence F. Chapman

10/17/2003 HVUONG1 00000114 09973646

01 FC:1251

110.00 OP